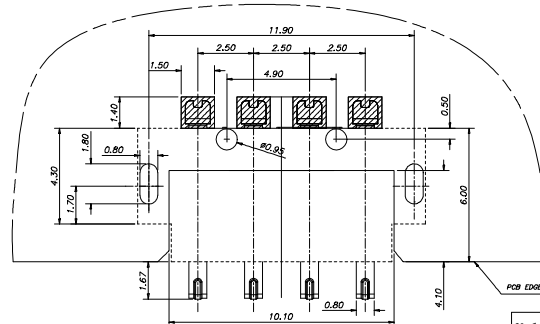
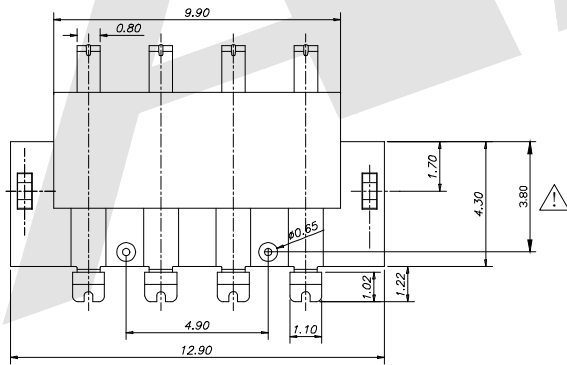
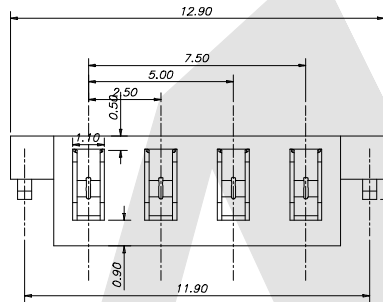
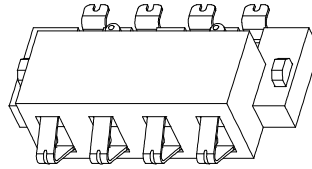
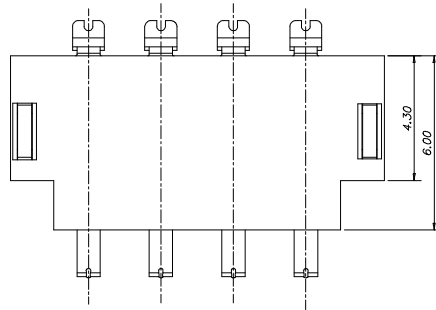


HSF



一般尺寸公差: ±0.05
PCB板布局

NOTES

- MATERIAL:
 - PIN: BERYLLIUM COPPER
 - INSULATOR: 30% GLASS-FILLED THERMOPLASTIC LCP OR EQUIVALENT UL94V-0, BLACK.
- FINISH: CONTACT FLASH(1* MIN.) ALL OVER, 50-100 MICROINCH (1.27-2.54 MICRON) NICKEL UNDERPLATED ALL OVER
SOLDER TAB: 50-100 (1.27-2.54 MICRON) MICROINCH MATTE TIN,
10-100 MICROINCH (1.27-2.54 MICRON) NICK UNDERPLATED
- ELECTRICAL SPECIFICATIONS:
 - VOLTAGE RATING: 250 VAC MIN
 - CURRENT RATING: 2.0 A MIN
 - DIELECTRIC STRENGTH: 1000 VAC FOR 1 MINUTE MIN
 - INSULATION RESISTANCE: 1000 MEG OHM MIN
 - CONTACT RESISTANCE: 30 MILL. OHM MAX
 - OPERATION TEMPERATURE: -55° C TO +125° C
 - PRODUCT WITHSTANDING REFLOW SOLDERING 260° FOR 10S
- MECHANICAL SPECIFICATIONS:
 - DURABILITY: 5,000 CYCLES
 - NORMAL FORCE AT MATED POSITION: 60g MIN
 - NORMAL FORCE AT FULL STROKE: 100g MIN
- PARTS TO BE PACKAGED IN ANTI-STATIC TAPE AND REEL FOR AUTOMATIC PLACEMENT.
- THE CAVITY IS 0.8±0.10mm HIGH WITH 0.10±0.10mm RECESSED FROM SURFACE.

Ordering Code:

ABT13 - 04 - L - B - X - D
① ② ③ ④ ⑤ ⑥

- | | |
|-----------------------|--------------------|
| ① Series No: | ⑤ Contact Plating: |
| ② No. of Contacts | G0: Gold flash |
| 04: 04Pin | G1: 3u" gold |
| ③ Insulator Material: | G2: 5u" gold |
| P: PBT+30%GF | G3: 10u" gold |
| L: LCP | G4: 15u" gold |
| ④ Pitch | G5: 30u" gold |
| B: 2.5mm Pitch | ⑥ Packing: |
| | A: Tray |
| | B: Bag |
| | C: Tube |
| | D: Tape Reel |

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

Antenk ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail: sales@antenk.com

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018

TITLE:
2.5mm Pitch 4P Battery Connector



DRAWING NO:	ABT13-04L BXD
PRODUCT NO:	ABT13-04L BXD

△ Add Size
DESCRIPTION

06/02/2021
DATE

REV